

# WEST·BOND® INC.

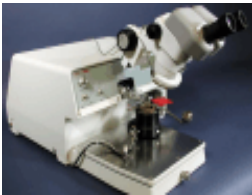
West-Bond manufactures wire bonders, die bonders, die attach, epoxy die attach, and pull tester for the semiconductor industry. Levels of automation vary from completely manual to fully automatic. With over 18,000 machines sold worldwide, designed and manufactured in the U.S.A. since 1966.

## MANUAL DIE BONDERS



### **Model 7200CR (Epoxy Die Bonder)**

This machine provides separate functions on the same tool head to dispense epoxy, then to pick up chips, rotate them into alignment, and place them.



### **Model 7316C (Eutectic Die Bonder)**

This machine allows to pick up and place chips and then bond them by the mechanical scrub, eutectic method. All operation is controlled by West-Bond's unique three-axis micromanipulator under microprocessor control.



### **Model 7327C (Multi-Collet Eutectic Die Bonder)**

This machine with a pneumatically operated turret mechanism to rotate into use position a succession of six differently sized die collets.



### **Model 7372E (Epoxy and Eutectic Die Bonders)**

This Dual-Head Die Bonders use the heads alternately to pick up chips; then rotate, place, and bond them. Both pick-up and bonding can be done by different methods, changeable by detachable heads.



### **Model 7367E (Eutectic Tweezer Die Bonder)**

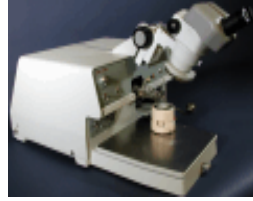
This machine with heads for mechanized tweezers pick up and placement of die, and for vacuum pick up and placement of preforms.



### **Model 7374E (Beam Lead Die Bonders)**

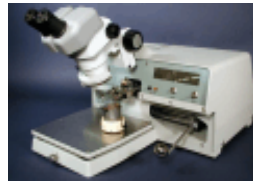
This machine adapted for ultrasonic bonding, with heat, of the tab leads of beam lead diodes. The right head is used for pick up of the tabbed die with provision for rotation at placement.

## MANUAL WIRE BONDERS



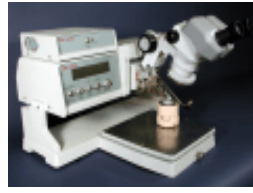
### **Model 7476D (Wedge-Wedge Wire Bonder)**

An ultrasonic / thermosonic wedge-wedge wire bonder designed to interconnect wire leads to semi-conductor, hybrid or microwave devices.



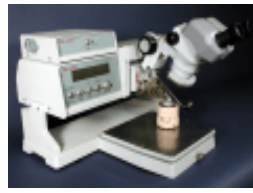
### **Model 7700D (Single Ball or Ball-Wedge Wire Bonder)**

A thermosonic ball-wedge wire bonder designed to interconnect wire leads to semiconductor, hybrid, or microwave devices.



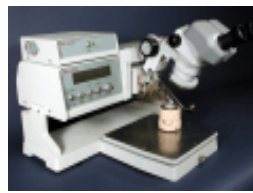
### **Model 7476E (Wedge-Wedge Wire Bonder)**

An ultrasonic / thermosonic wedge-wedge wire bonder designed to interconnect wire leads to semi-conductor, hybrid or microwave devices.



### **Model 747677E (Wedge-Wedge and Ball-Wedge Wire Bonders)**

Manual Wire Bonders capable of both Wedge/Wedge and Wedge/Ball bonding in one machine.



### **Model 7700E (Single Ball or Ball-Wedge Wire Bonder)**

A thermosonic ball-wedge wire bonder designed to interconnect wire leads to semiconductor, hybrid, or microwave devices.

## WIRE PULL TESTER



### **Model 70PTE (Wire Pull Tester)**

Provides an exceptionally convenient means to place a hook under the arch of a bonded wire and then lower the wire under microprocessor control to measure tensile strength, either destructively or non-destructively.

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## SEMI-AUTOMATIC WIRE AND BALL BONDRERS



### **Model 4546E (Semi-Automatic Wedge-Wedge Wire Bonder, Motorized Z and Y Axes, With Loop Shape Control)**

This machine was revolutionary at its inception as the first to make a wire bond connection fully under programmable software control executed digitally by motors, thus making possible the manufacture of high frequency, high power semiconductor devices where connections must be identical.



### **Model 4700E (Semi-Automatic Ball-Wedge Wire Bonder --or Single-Ball Bonder, Motorized Z and Y Axes)**

Notably the placement of all machine mechanism above the work plane to allow unlimited access, and the setting of axis brakes to lock on target.



### **Model 454647E (Semi-Automatic Wedge-Wedge & Ball-Wedge Wire Bonder, With Loop Shape Control)**

Capable of both Wedge/Wedge and Wedge/Ball bonding in one machine.

## AUTOMATIC WIRE AND BALL BONDRERS



### **Model 3536E (Automatic, Gantry, Large Area, Wedge Bonder)**

Two-Way Convertibility, 45° Wire Feed, or 90° Wire and Ribbon Feed.

The program runs under Windows XP Professional and is executed by a Pentium 4 processor housed in an Industrial CPU enclosure. The User Interface is displayed on a large LCD color display, and consists of many screen forms for user interaction. It allows to locate and bond automatically fine wire connections arrayed over a large stationary work piece.



### **Model 3700E (Automatic, Gantry, Large Area, Ball Bonder)**

Single Ball or Ball-Wedge Bonder. There is no limit to the size of the work as this machine is entirely above the bond plane. The area traversed for bonding is five and three-eighths by nine and one-half inches; and successive areas could be presented.



### **Model 353637E (Automatic, Gantry, Large Area, Wedge & Ball Bonder)**

Automatic Wire Bonder capable of both Wedge/Wedge and Wedge/Ball bonding in one machine.



Vietnam's leading supplier of semiconductor interconnect assembly equipment.

[www.acrosemi.com](http://www.acrosemi.com)

Email: [sales@acrosemi.com](mailto:sales@acrosemi.com)

#### **U.S.A Office**

4930 W. Flight Ave.,  
Santa Ana, California 92704, U.S.A.  
Tel: 714-468-9034  
Fax: 866-212-8857  
Email: [sales@acrosemi.com](mailto:sales@acrosemi.com)

#### **Ho Chi Minh Office**

404 Plot G, Tan Binh IZ, Tan Phu Dist.,  
Ho Chi Minh City, Vietnam  
Tel: (+84 8) 6 674-2919  
Fax: (+84 8) 3 815-7077  
Email: [hcmc@acrosemi.com](mailto:hcmc@acrosemi.com)

#### **Hanoi Office**

1, Dai Co Viet Road,  
Hanoi City, Vietnam  
Tel: (+84) 91-225-7173  
Fax: (+001) 866-212-8857  
Email: [hanoi@acrosemi.com](mailto:hanoi@acrosemi.com)